

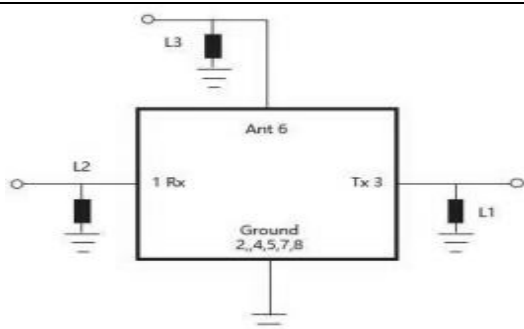
	1980-2400	dB	45	51	-
	2400-2500	dB	43	54	-
	2517-2592	dB	43	54	-
	2607-2682	dB	43	54	-
	3476-3576	dB	43	55	-
	4345-4470	dB	43	55	-
	4900-5950	dB	35	40	-
Isolation	824-849	dB	53	57	-
	869-894	dB	50	58	-
	1574-1577	dB	50	58	-
	1683-1708	dB	50	58	-
	2462-2577	dB	43	55	-
Operation Temperature	-20℃~+85℃	℃	-	-	-
Storage Temperature	-40℃~+85℃	℃	-	-	-
RF Power Dissipation	+29	dBm	-	-	-

Remark

Note 1: Test Temperature: 25℃±2℃

Note 2: Terminating source impedance: 50Ω. Terminating load impedance: 50Ω

(3)Test Circuit



Port	Matching Component
Tx	L1 :12.0 nH (Ideal inductor)
Rx	L2 :17.0 nH (Ideal inductor)
Ant	L3 : 9.0 nH (Ideal inductor)

Figure 1 Electrical Characteristics: Tx to Ant.

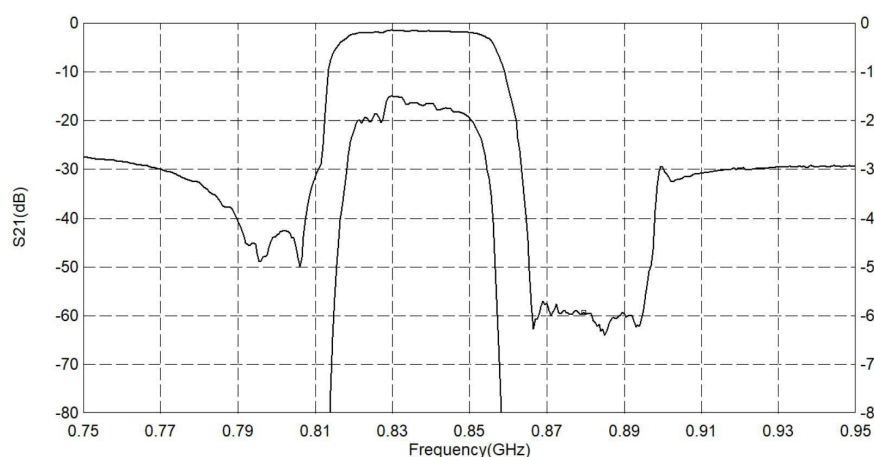


Figure 2 Electrical Characteristics: Tx to Ant.

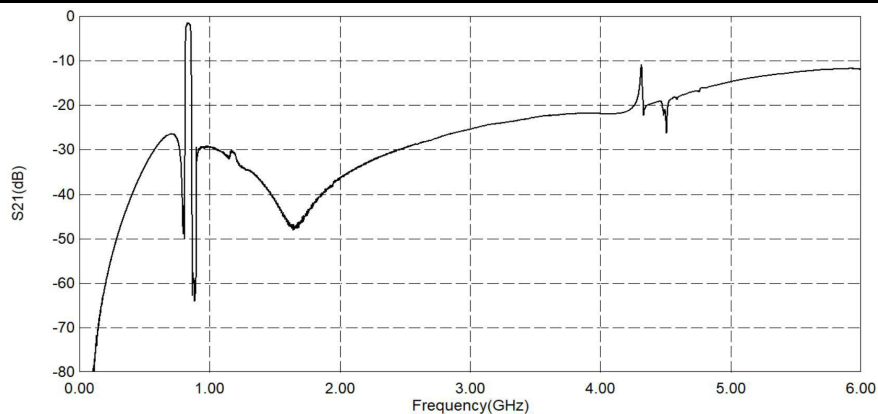


Figure 3 Electrical Characteristics: Ant to Rx.

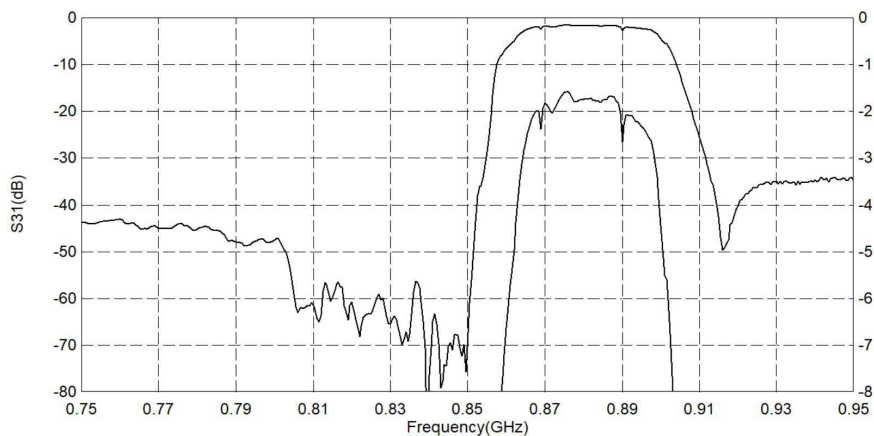


Figure 4 Electrical Characteristics: Ant to Rx.

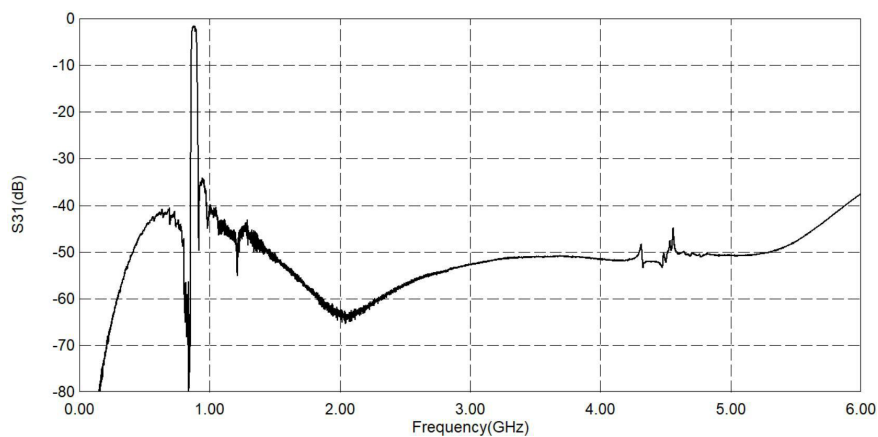


Figure 5 Electrical Characteristics: Tx to Rx.

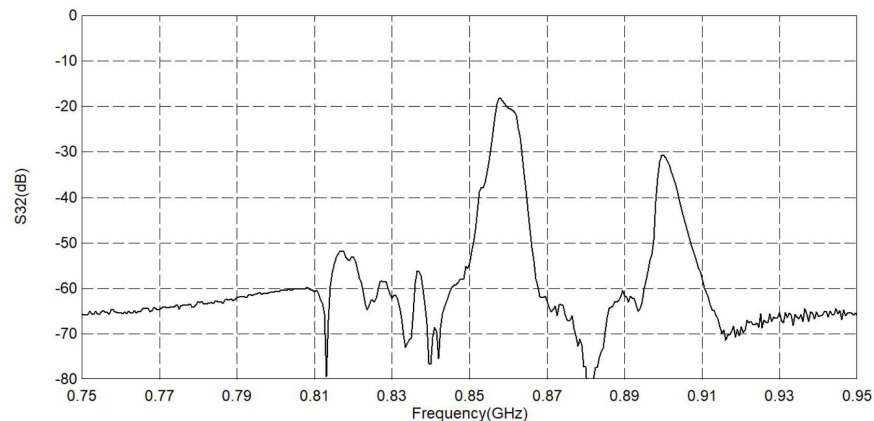


Figure 6 Electrical Characteristics: Tx to Rx.

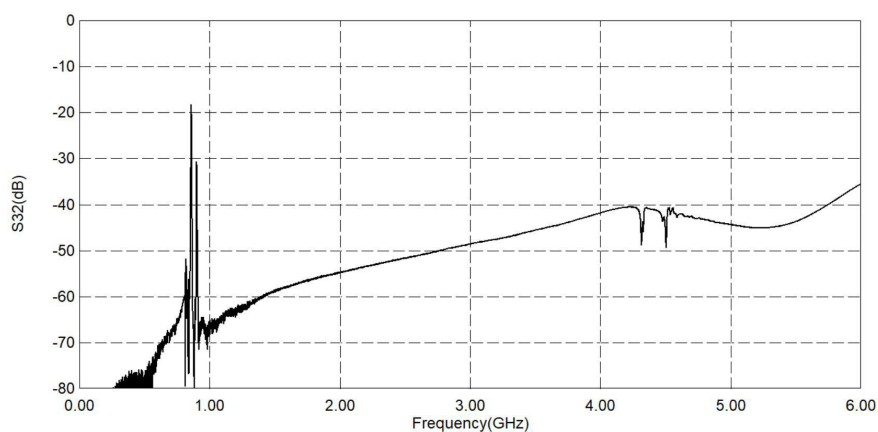
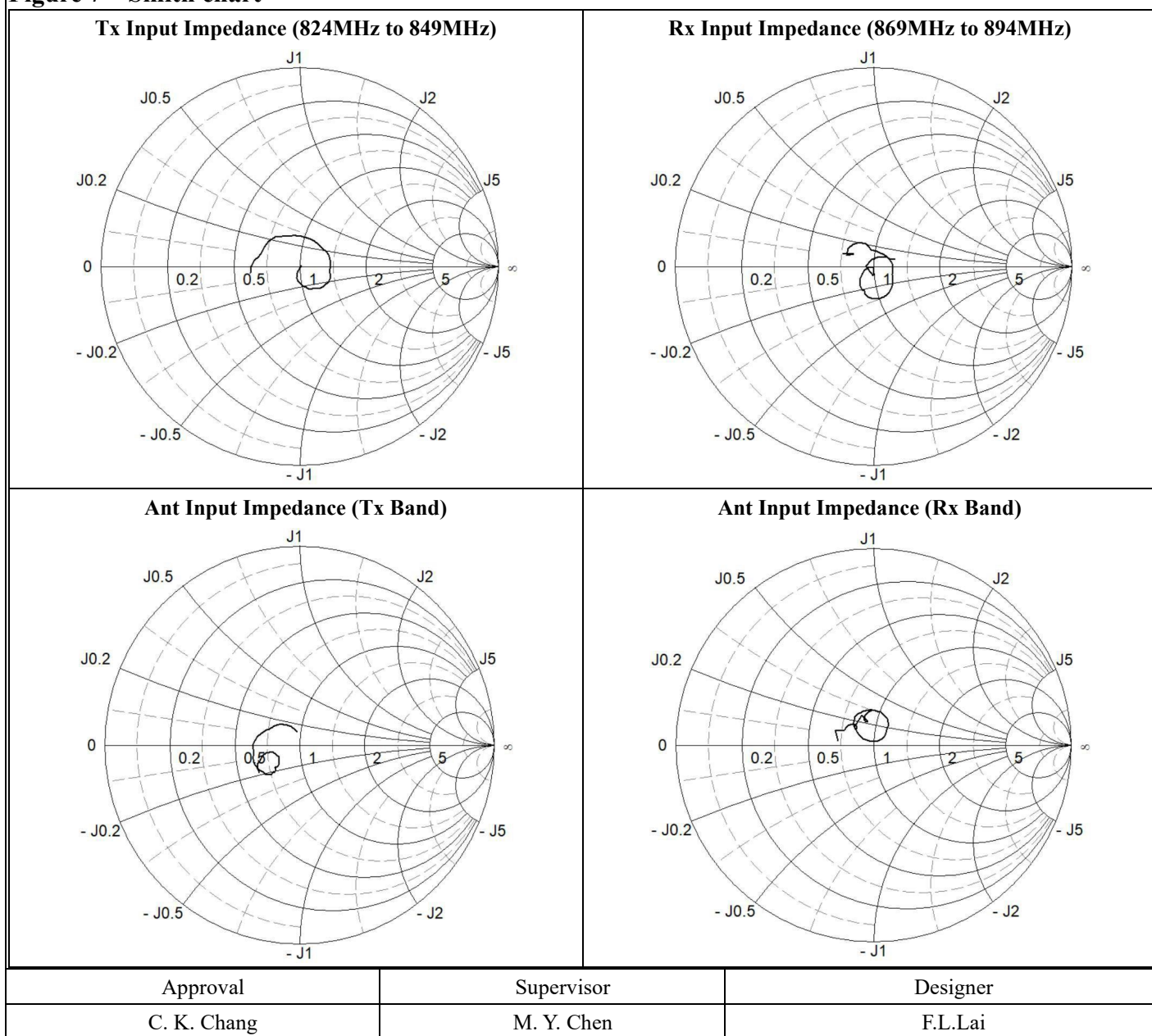
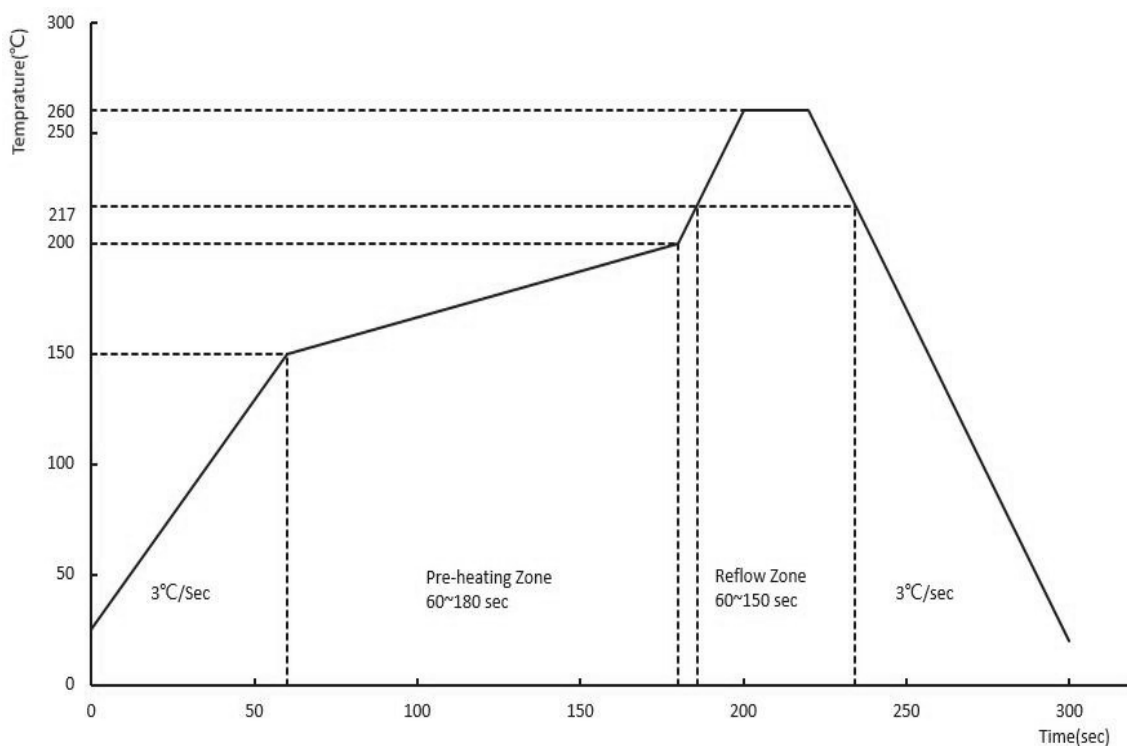


Figure 7 Smith chart



Recommended SMT Solder Profile



Reliability

No.	Test item	Test condition	
1	Temperature Storage	Temperature: 85°C±2°C , Duration: 250h , Recovery time: 2h±0.5h Temperature: -40°C±3°C , Duration: 250h ,Recovery time: 2h±0.5h	
2	Humidity Test	Conditions: 60°C±2°C ,90~95%RH	Duration:250h
3	Thermal Shock	Heat cycle conditions: TA=-40°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.	
4	Vibration Fatigue	Frequency of vibration:10~55Hz Directions: X,Y and Z	Amplitude:1.5mm Duration: 2h
5	Drop Test	Cycle time:10times	Height:1.0m
6	Solder Ability Test	Temperature:245°C±5°C Depth: DIP--2/3, SMD--1/5	Duration:3.0s--5.0s
7	Resistance to Soldering Heat	Thickness of PCB:1mm , Solder condition: 260°C±5°C , Duration:10±1s Temperature of Soldering Iron: 350°C±10°C, Duration: 3~4s, Recovery time : 2 ± 0.5h	